

### **AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning on line 23 of page 4 of the original specification with the following amended paragraph.

In each pixel, the intermediate second metal film 28 serves as a light blocking metal film to block part of read light L made incident to an upper transparent substrate 42 (to be explained later) from reaching the MOSFET 14 formed under the metal film 28 on the p-type Si substrate 11. Namely, the second metal film (light blocking metal film) 28 is formed to cover an opening 30a formed between adjacent metal films 30 formed over the film 28 and block part of read light L entering the opening 30a. The second metal film 28 is connected to the lowermost first metal film 26 through the aluminum wiring filled in the second via hole Via2 etched in the second interlayer insulating film 27. In some embodiments, as shown in Figures 4 and 12, the light blocking metal film 28 is divided into a first portion 91 and a second portion 92 by an annular-type opening 28a, which is bound on its interior edge by the first portion 91 and is in turn bound on its exterior edge by the second portion 92. Opening 28a thus electrically isolates the first portion 91 from the second portion 92.

Please add the following paragraph at line 23 of page 20 of the specification.

Fig.12 is a sectional view of an embodiment of Fig. 4 taken along the XII – XII line.